PMP10236 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C5	2	15uF	UVC2G150MPD	Nichicon	CAP ALUM 15UF 400V 20% RADIAL	RCAP, 10x25mm
C2	1	680uF	EKZE100ELL681MH15D	Nippon Chemi-Con	CAP ALUM 680uF 10V 20% RADIAL	RCAP_8x15mm
C3	1	4.7uF	CGB3B1X5R1A475K055AC	TDK	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0603	0603
C4	1	22uF	CL10A226MP8NUNE	Samsung	CAP, CERM, 22 µF, 10 V, +/- 20%, X5R, 0603	0603
C6	1	2200pF	DE1E3KX222MA5BA01	MuRata	CAP, CERM, 2200 pF, 250 V, +/- 20%, E, Disc 10x8mm	Disc 10x8mm
C7	1	220uF	EKZE250ELL221MHB5D	Nippon Chemi-Con	CAP ALUM 220UF 25V 20% RADIAL	RCAP 8x13mm
C8	1	2.2uF	GRM316R61E225KA12D	MuRata	CAP, CERM, 2.2 µF, 25 V, +/- 10%, X5R, 1206	1206
C9	1	4.7uF	C2012X5R1E475K125AB	TDK	CAP, CERM, 4.7 µF, 25 V, +/- 10%, X5R, 0805	0805
C10	1	10uF	C3225X5R1H106K250AB	TDK	CAP, CERM, 10 μF, 50 V, +/- 10%, X5R, 1210	1210
D1	1	SS1H10-E3/61T	SS1H10-E3/61T	Vishay-Semiconductor	Diode, Schottky, 100V, 1A, SMA	SMA
D2	1	200V	3SMAJ5956B	Micro Commercial Co	DIODE ZENER 200V 3W DO214AC	SMA
D3	1	DF10SA	DF10SA	Vishay-Semiconductor	Diode, Switching-Bridge, 1000V, 1A, DF-S	DF-S
04	1	US1M-13-F	US1M-13-F	Diodes Inc.	Diode, Ultrafast, 1000V, 1A, SMA	SMA
D5	1	SS1200-LTP	SS1200-LTP	Micro Commercial Compor	nent DIODE SCHOTTKY 200V 1A SMA	SMA
D6, D100	2	BAS20HT1G	BAS20HT1G	•	DIODE SWITCH 200V 200MA SOD323	SOD-323
D101	1	27V	MMSZ5254BS-7-F	Diodes Inc.	Diode, Zener, 27 V, 200 mW, SOD-323	SOD-323
J1	1	1-1318301-3	1-1318301-3	TE Connectivity	HEADER, .312 VERT 3POS	19.7x10.7 x8.5 mm
_1, L2	2	100uH	7447462101	Wurth Elektronik eiSos	Inductor, Unshielded Drum Core, Ferrite, 100uH, 0.8A, 0.457 ohm, TH	D6 x 8.5mm
Q1	1	2V	FJI5603DTU	Fairchild	TRANSISTOR NPN 800V 3A I2PAK	TO-126
R1, R3, R4, R6	4	4.7Meg	CRCW12064M70JNEA	Vishay-Dale	RES, 4.7Meg ohm, 5%, 0.25W, 1206	1206
R2	1	511	CRCW0603511RFKEA	Vishay-Dale	RES, 511, 1%, 0.1 W, 0603	0603
R5	1	1.00k	CRCW08051K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.125W, 0805	0805
R7	1	2.0k	CRCW08052K00JNEA	Vishay-Dale	RES, 2.0k ohm, 5%, 0.125W, 0805	0805
R8, R10, R12	3	1.00Meg	CRCW12061M00FKEA	Vishay-Dale	RES, 1.00 M, 1%, 0.25 W, 1206	1206
R9	1	0	RC1206JR-070RL	Yageo America	RES, 0, 5%, 0.25 W, 1206	1206
R11, R100	2	36.5k	CRCW060336K5FKEA	Vishay-Dale	RES, 36.5 k, 1%, 0.1 W, 0603	0603
R13	1	324	CRCW1206324RFKEA	Vishay-Dale	RES, 324, 1%, 0.25 W, 1206	1206
R14	1	15.4k	CRCW060315K4FKEA	Vishay-Dale	RES, 15.4 k, 1%, 0.1 W, 0603	0603
R15	1	3.0	CRCW08053R00JNEA	Vishay-Dale	RES, 3.0 ohm, 5%, 0.125W, 0805	0805
RF1	1	10.0	1879229-4	TE Connectivity	RES 10.0 OHM 1/8W 5% 1206	1206
<u></u> Г1	1	2.86mH	DCT19EPC-XxxH014	TDK	Transformer, Flyback, 2.86mH, TH	23.3x18.75x33 mm
ΓΡ1, TP3	2	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
ГР2, ТР4	2	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
J1	1	UCC28722DBV	UCC28722DBV	Texas Instruments	Constant-Voltage, Constant-Current Controller With Primary-Side Regulation, BJT Drive, DBV0006A	DBV0006A

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